

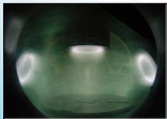
TFSP - 995 SPUTTERING SYSTEM



- Equipped with three 6" semi-unbalanced magnetron sputter sources
- Independent gas showers for each gun with MFC
- Three independent DC Pulse 5kW power supplies
- Adjustable source to substrate distance
- Simultaneous deposition from up to three sputter sources
- Independent crystal heads for each source
- 300mm diameter substrate
- Special Rotating Stage, RF/DC bias compatible
- Constant Pressure / Constant flow modes with throttle valve
- Additional gas inlet with MFC
- Fully Automatic Control PC/PLC
- Human Machine Interface software

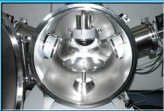
Benefits:

- Allows coating of large 3D samples
- Allows pure metal films deposition
Allows reactive sputtering of fine grain oxides
- High density films
- High deposition rates
- Easy to operate
- Process recipes PC builder
- Historical data records
- Fully adaptable to a wide range of processes
- Repeatable film thickness depositions
- Easy loading and unloading of samples



Technical Data:

Chamber:	600 mm nom diameter x 600 mm depth stainless steel water-cooled cylinder, horizontal axe, front door, one view port
Ultimate pressure:	less than 2×10^{-7} Torr
Pump Down Time:	5×10^{-6} Torr in 45 min
Number of sources:	3 ea of MAK 6"
Power supply:	3 ea of Pinnacle™ Plus + 5kW MDX-500, 500 W (bias)
Gas Flow:	4 channels of MFC 100sccm, bellow sealed stainless steel valves each
Thickness monitor:	SQM-242 PCI Card
Number of crystal heads:	3
Control:	PC/PLC



Contact



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